

Listing of Claims:

Claims 1 -27 (Canceled)

28. (Currently Amended) ~~The A~~ process for the manufacture of a reflection transfer and for applying the transfer to a substrate that is not clear translucent, comprising the steps:

initially providing an adhesive-repellent base medium;

applying a transfer adhesive ~~of the assembled reflection transfer~~ on the base medium, wherein the transfer adhesive is at least one of heat sensitive and pressure sensitive;

applying an intermediate ink layer onto a side of said transfer adhesive opposite said base medium;

applying a reflection ink layer comprising a plurality of reflection particles directly onto said intermediate ink layer, wherein said reflection particles are added to the reflection ink before applying the reflection ink on the ~~transfer adhesive or the~~ intermediate ink layer, ~~respectively~~;

drying the transfer such that at least some of the reflection particles are raised above the reflection ink layer;

wherein said intermediate ink layer is not clear translucent; ~~and~~

removing said adhesive repellent base medium to form an open face on said reflection transfer;

applying said open face of said reflection transfer onto said substrate; and

forming the reflection transfer on said substrate ~~via a screen printing process.~~

29. (Currently Amended) The A process for the manufacture of a reflection transfer and for applying the transfer to a substrate that is not clear translucent, comprising the steps:

initially providing an adhesive-repellent base medium;

applying onto the base medium one of a) a transfer adhesive/reflection ink mixture containing a plurality of reflection particles and b) a colored transfer adhesive which contains a plurality of reflection particles of the ~~assembled~~ reflection transfer;

wherein at least one of the transfer adhesive/reflection ink mixture and the colored transfer adhesive is not clear translucent;

drying the transfer such that at least some of the reflection particles are raised above the mixture; ~~and~~

removing said adhesive repellent base medium to form an open face on said reflection transfer;

applying said open face of said reflection transfer onto said substrate; and

forming the reflection transfer on said substrate ~~via a screen printing process.~~

30. (Currently Amended) The A process for the manufacture of a reflection transfer ~~that is not clear translucent,~~ and for applying the transfer to a substrate comprising the steps:

initially providing an adhesive repellent base medium in a screen printing machine;

applying a transfer adhesive ~~of the assembled reflection transfer~~ on the base medium, wherein the transfer adhesive is at least one of heat sensitive and pressure sensitive;

applying a reflection ink layer comprising a plurality of reflection particles directly onto said transfer adhesive wherein said reflection particles are added to the reflection ink before applying the reflection ink on the transfer adhesive;

drying the transfer such that at least some of the reflection particles are raised above the reflection in layer; and

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removing said adhesive repellent base medium to form an open face on said reflection transfer;

applying said open face of said reflection transfer onto said substrate; and

wherein said transfer adhesive is not translucent.

31. (Previously Presented) The process as in claim 30, wherein said step of applying said transfer adhesive to said base medium comprises applying said transfer adhesive via a screen printing process.

32. (Previously Presented) The process as in claim 28, further comprising the step of applying said reflection transfer to a substrate by using a transfer press.

33. (Currently Amended) The process as in claim 29, further comprising the step of applying said reflection transfer ~~to~~ to a substrate by using a transfer press.

34. (Previously Presented) The process as in claim 28, wherein the process proceeds sequentially in the order in which the steps are presented.

35. (Previously Presented) The process as in claim 29, wherein the process proceeds sequentially in the order in which the steps are presented.

36. (Previously Presented) The process as in claim 30, wherein the process proceeds sequentially in the order in which the steps are presented.

37. (New) A process for the manufacture of a reflection transfer and for applying the transfer to a substrate, comprising the steps:

initially providing an adhesive-repellent base medium;

applying a transfer adhesive on the base medium, wherein the transfer adhesive is at least one of heat sensitive and pressure sensitive;

applying an intermediate ink layer onto a side of said transfer adhesive opposite said base medium;

applying a reflection ink layer comprising a plurality of reflection particles directly onto said intermediate ink layer, wherein said reflection particles are added to the reflection ink before applying the reflection ink on the intermediate ink layer;

drying the transfer such that at least some of the reflection particles are raised above the reflection ink layer;

wherein said intermediate ink layer is not clear translucent; and

wherein said adhesive repellent base medium is configured to be removable to form an open face on said reflection transfer, said open face for application to a substrate.

38. (New) The process as in claim 28, wherein said reflection ink layer forms a face opposite said open face to form a reflective surface on said substrate after said open face is applied to said substrate.

39. (New) The process as in claim 29, wherein said reflection ink layer forms a face opposite said open face to form a reflective surface on said substrate after said open face is applied to said substrate.

40. (New) The process as in claim 30, wherein said reflection ink layer forms a face opposite said open face to form a reflective surface on said substrate after said open face is applied to said substrate.



41. (New) The process as in claim 37, wherein said reflection ink layer forms a face opposite said open face to form a reflective surface on said substrate after said open face is applied to said substrate.